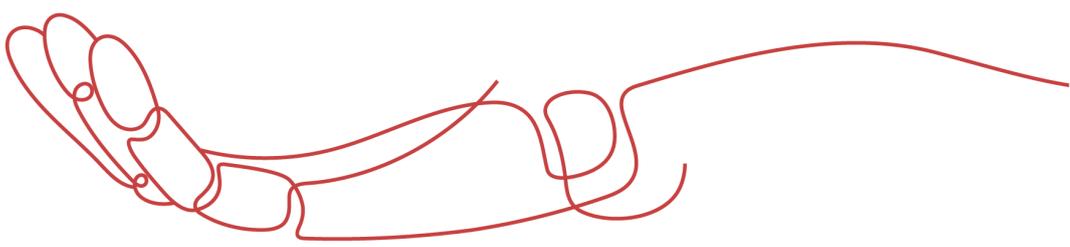


PRODUCT DATA SHEET



To learn more about JGSEMI, please visit our website at



Datasheet



Resources



Samples

Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.jg-semi.cn. Please email any questions regarding the system integration to JINGAO_questions@jgsemi.com.

General Description

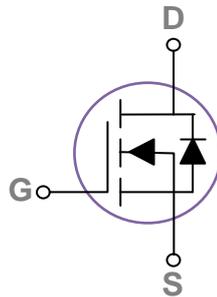
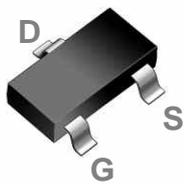
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

| | | |
|-------|-------|------|
| BVDSS | RDSON | ID |
| 20V | 16mΩ | 6.5A |

Features

- 20V, 6.5A, RDS(ON)=16mΩ@VGS=4.5V
- Improved dv/dt capability
- Fast switching
- Green Device Available

SOT-23 Pin Configuration



Applications

- Notebook
- Load Switch
- Hand-Held Instruments

Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

| Symbol | Parameter | Rating | Units |
|-----------|--|------------|---------------------|
| V_{DS} | Drain-Source Voltage | 20 | V |
| V_{GS} | Gate-Source Voltage | ± 12 | V |
| I_D | Drain Current – Continuous ($T_c=25^\circ\text{C}$) | 6.5 | A |
| | Drain Current – Continuous ($T_c=100^\circ\text{C}$) | 4.2 | A |
| I_{DM} | Drain Current – Pulsed ¹ | 26.8 | A |
| P_D | Power Dissipation ($T_c=25^\circ\text{C}$) | 1.56 | W |
| | Power Dissipation – Derate above 25°C | 0.012 | W/ $^\circ\text{C}$ |
| T_{STG} | Storage Temperature Range | -55 to 150 | $^\circ\text{C}$ |
| T_J | Operating Junction Temperature Range | 150 | $^\circ\text{C}$ |

Thermal Characteristics

| Symbol | Parameter | Typ. | Max. | Unit |
|-----------------|--|------|------|--------------------|
| $R_{\theta JA}$ | Thermal Resistance Junction to ambient | --- | 80 | $^\circ\text{C/W}$ |

Electrical Characteristics ($T_J=25\text{ }^\circ\text{C}$, unless otherwise noted)
Off Characteristics

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|------------------------------|------------------------------------|--|------|------|-----------|--------------------|
| BV_{DSS} | Drain-Source Breakdown Voltage | $V_{GS}=0V, I_D=250\mu A$ | 20 | --- | --- | V |
| $\Delta BV_{DSS}/\Delta T_J$ | BV_{DSS} Temperature Coefficient | Reference to $25\text{ }^\circ\text{C}$, $I_D=1mA$ | --- | 0.02 | --- | $V/^\circ\text{C}$ |
| I_{DSS} | Drain-Source Leakage Current | $V_{DS}=20V, V_{GS}=0V, T_J=25\text{ }^\circ\text{C}$ | --- | --- | 1 | μA |
| | | $V_{DS}=16V, V_{GS}=0V, T_J=125\text{ }^\circ\text{C}$ | --- | --- | 10 | μA |
| I_{GSS} | Gate-Source Leakage Current | $V_{GS}=\pm 10V, V_{DS}=0V$ | --- | --- | ± 100 | nA |

On Characteristics

| | | | | | | |
|---------------------|--------------------------------------|-------------------------------|-----|-----|-----|---------------------|
| $R_{DS(ON)}$ | Static Drain-Source On-Resistance | $V_{GS}=4.5V, I_D=4A$ | --- | 16 | 22 | m Ω |
| | | $V_{GS}=2.5V, I_D=3A$ | --- | 18 | 24 | |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{GS}=V_{DS}, I_D=250\mu A$ | 0.3 | 0.6 | 1.1 | V |
| $\Delta V_{GS(th)}$ | $V_{GS(th)}$ Temperature Coefficient | | --- | 2 | --- | $mV/^\circ\text{C}$ |
| gfs | Forward Transconductance | $V_{DS}=10V, I_S=4A$ | --- | 9.5 | --- | S |

Dynamic and switching Characteristics

| | | | | | | |
|--------------|------------------------------------|---|-----|------|-----|----|
| Q_g | Total Gate Charge ^{2,3} | $V_{DS}=10V, V_{GS}=4.5V, I_D=4A$ | --- | 5.8 | --- | nC |
| Q_{gs} | Gate-Source Charge ^{2,3} | | --- | 0.6 | --- | |
| Q_{gd} | Gate-Drain Charge ^{2,3} | | --- | 2 | --- | |
| $T_{d(on)}$ | Turn-On Delay Time ^{2,3} | $V_{DD}=10V, V_{GS}=4.5V, R_G=25\Omega$ $I_D=1A$ | --- | 5.0 | --- | nS |
| T_r | Rise Time ^{2,3} | | --- | 14.4 | --- | |
| $T_{d(off)}$ | Turn-Off Delay Time ^{2,3} | | --- | 30.0 | --- | |
| T_f | Fall Time ^{2,3} | | --- | 9.2 | --- | |
| C_{iss} | Input Capacitance | $V_{DS}=10V, V_{GS}=0V, F=1MHz$ | --- | 600 | --- | pF |
| C_{oss} | Output Capacitance | | --- | 70 | --- | |
| C_{rss} | Reverse Transfer Capacitance | | --- | 45 | --- | |

Drain-Source Diode Characteristics and Maximum Ratings

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|----------|---------------------------|---|------|------|------|------|
| I_S | Continuous Source Current | $V_G=V_D=0V$, Force Current | --- | --- | 6.5 | A |
| I_{SM} | Pulsed Source Current | | --- | --- | 13 | A |
| V_{SD} | Diode Forward Voltage | $V_{GS}=0V, I_S=1A, T_J=25\text{ }^\circ\text{C}$ | --- | --- | 1.2 | V |

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.

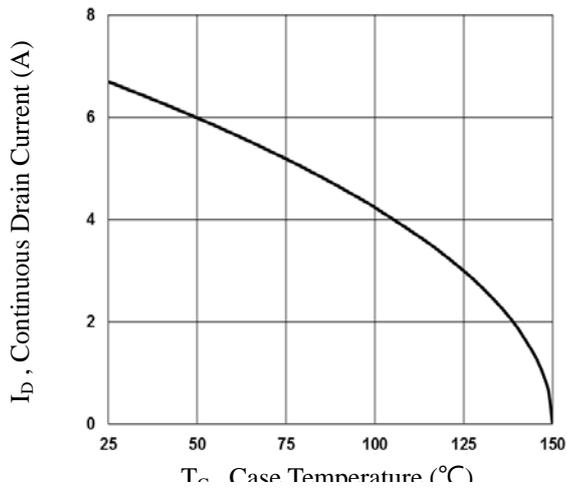


Fig.1 Continuous Drain Current vs. T_C

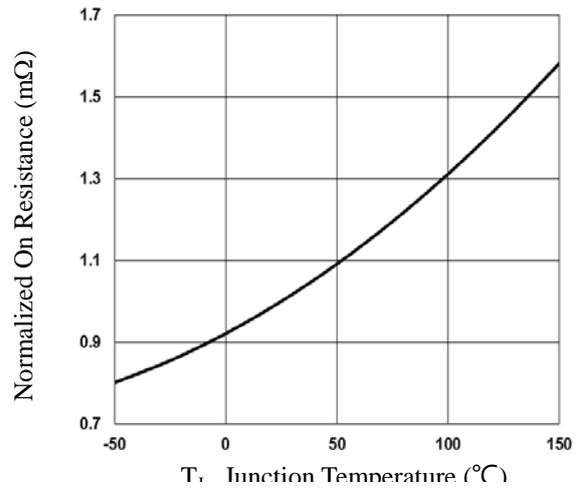


Fig.2 Normalized $R_{DS(on)}$ vs. T_J

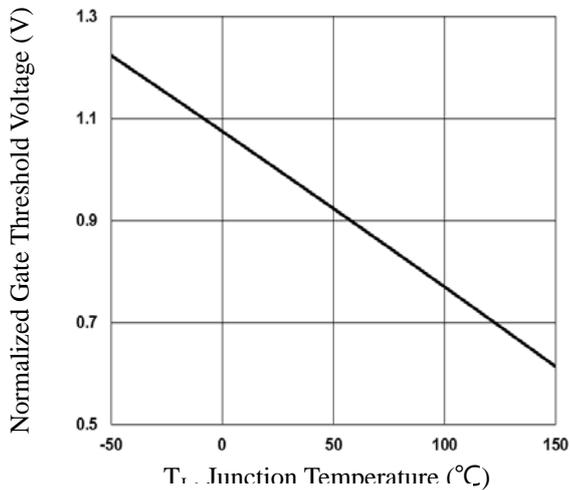


Fig.3 Normalized V_{th} vs. T_J

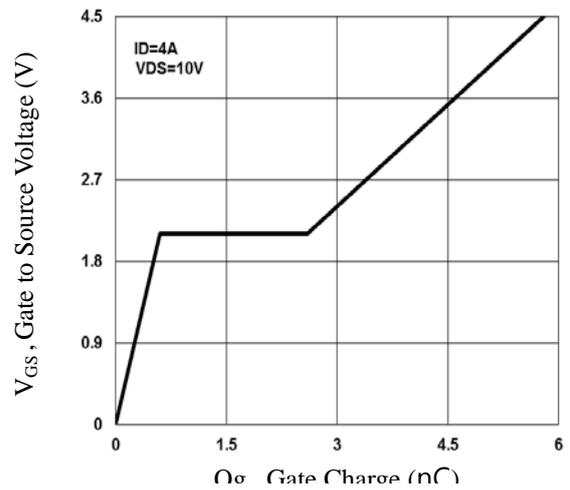


Fig.4 Gate Charge Waveform

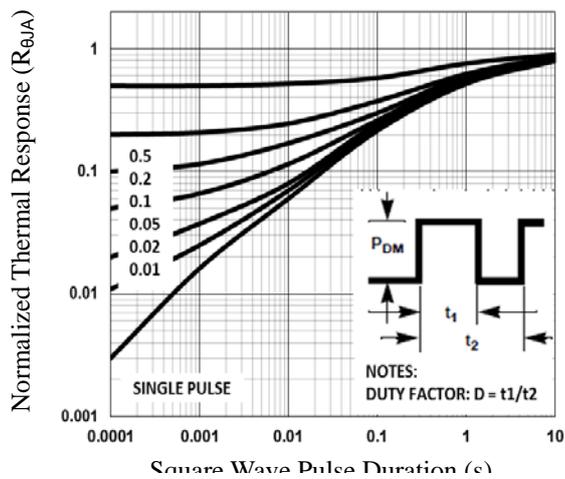


Fig.5 Normalized Transient Impedance

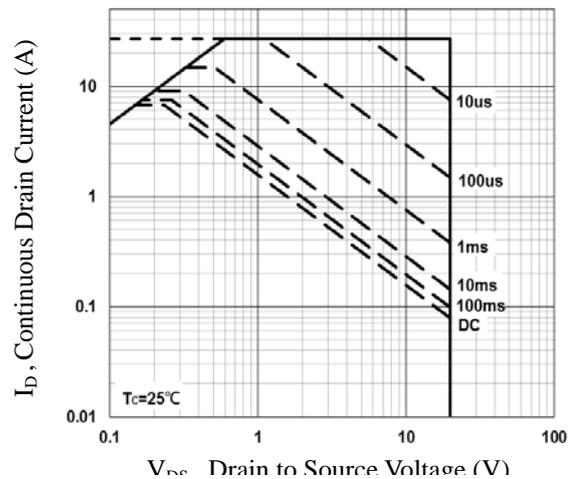


Fig.6 Maximum Safe Operation Area

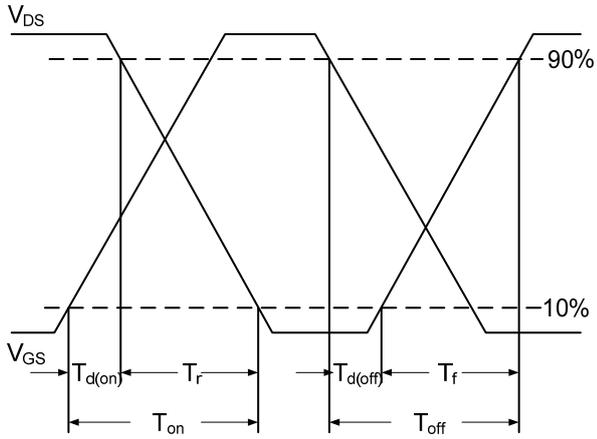


Fig.7 Switching Time Waveform

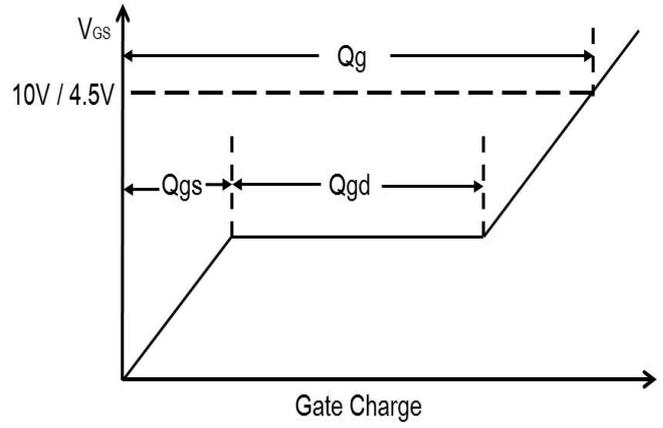
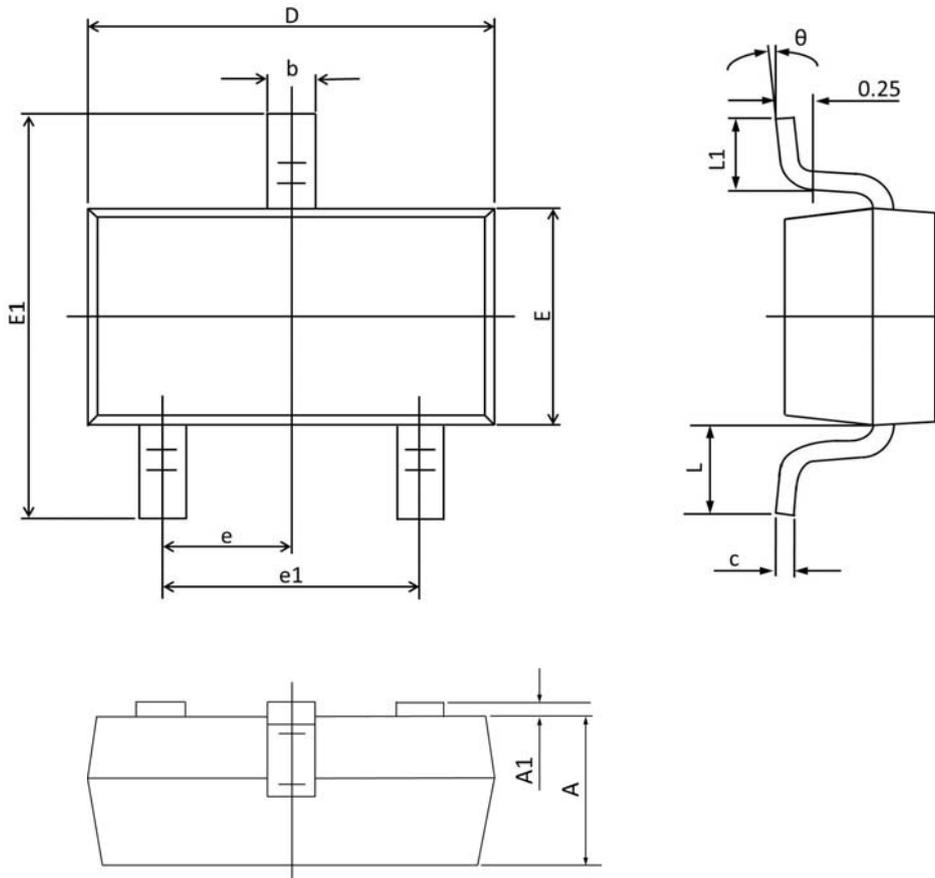


Fig.8 Gate Charge Waveform

SOT-23 PACKAGE INFORMATION



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|----------|---------------------------|-------|----------------------|-------|
| | Min | Max | Min | Max |
| A | 0.900 | 1.000 | 0.035 | 0.039 |
| A1 | 0.000 | 0.100 | 0.000 | 0.004 |
| b | 0.300 | 0.500 | 0.012 | 0.020 |
| c | 0.090 | 0.110 | 0.003 | 0.004 |
| D | 2.800 | 3.000 | 0.110 | 0.118 |
| E | 1.200 | 1.400 | 0.047 | 0.055 |
| E1 | 2.250 | 2.550 | 0.089 | 0.100 |
| e | 0.950 TYP. | | 0.037 TYP. | |
| e1 | 1.800 | 2.000 | 0.071 | 0.079 |
| L | 0.550 REF. | | 0.022 REF. | |
| L1 | 0.300 | 0.500 | 0.012 | 0.020 |
| θ | 1° | 7° | 1° | 7° |

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